



Material Content Data Sheet



Sales Product Name		SAK-C167SR-LM HA+		Issued		29. August 2013			
MA#		MA000972160							
Package		PG-MQFP-144-8		Weight*		4197.93 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	25.986	0.62	0.62	6190	6190	
leadframe	non noble metal	magnesium	7439-95-4	0.976	0.02		232		
	inorganic material	silicon	7440-21-3	4.227	0.10		1007		
	non noble metal	nickel	7440-02-0	19.510	0.46		4648		
	non noble metal	copper	7440-50-8	625.625	14.90	15.48	149032	154919	
wire	noble metal	gold	7440-57-5	7.263	0.17	0.17	1730	1730	
encapsulation	organic material	carbon black	1333-86-4	10.438	0.25		2487		
	plastics	epoxy resin	-	441.893	10.53		105264		
	inorganic material	silicondioxide	60676-86-0	3027.140	72.13	82.91	721102	828853	
leadfinish	non noble metal	tin	7440-31-5	19.066	0.45	0.45	4542	4542	
plating	noble metal	silver	7440-22-4	10.582	0.25	0.25	2521	2521	
glue	plastics	acrylic resin	-	1.045	0.02		249		
	noble metal	silver	7440-22-4	4.180	0.10	0.12	996	1245	
*deviation	< 10%					Sum in total:	100,00		1000000

Important Remarks:

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Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com